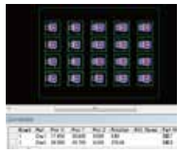
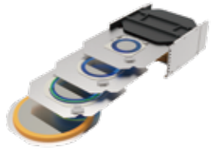
Features

Functions for high-mix production



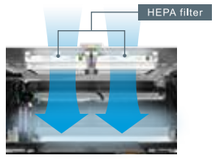
- Production can be continued because programs are created at an external computer.
- Production with high-accuracy and high-quality placements can be achieved by automatically performing calibration when nozzles and pots are exchanged.

Wafer map display



By automatically reading the wafer ID, the correct data can always be acquired. Data can be switched by automatically reading wafer IDs.

Inside the machine is kept clean



By installing a HEPA filter* with a particle collection efficiency of 99.97% or more in the machine the clean level in the machine is improved.

*: Option

Maintenance guidance

Heads, feeders, and nozzles have individual IDs, so reliable maintenance can be performed based on management and guidance from the system. Stable production can be performed with equipment in good condition all the time.

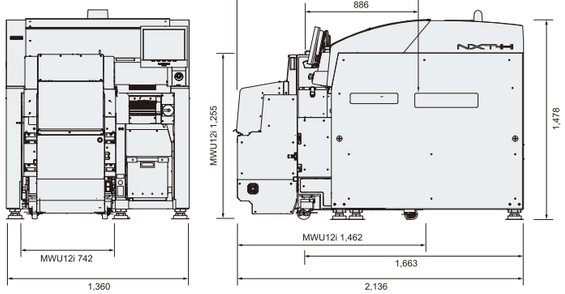
Specifications

				type FC	type SD	type LD
Heads				G04FQ	H24S / H24G	H08MQ
Die	Placement accuracy *1			±0.008 mm	±0.020 mm	±0.015 mm
	Die size *2			0.5 x 0.5 to 15 x 15 mm	0.5 x 0.5 to 5.0 x 5.0 mm	0.5 x 0.5 to 24 x 24 mm
	Die thickness			0.08 to 6.5 mm	0.08 to 3 mm	0.08 to 6.5 mm
	Minimum bump size			0.050 mm	-	-
	Bump pitch			0.100 mm	-	-
	Throughput *1	NXT-H	Face-up	4,500 cph	13,400 cph	8,700 cph
			Face-down	6,100 cph	-	-
				4,000 cph *3	-	-
	Wafer size			4 to 12 inch		
	Wafer magazine			25 or 13 slots		
SMD	Placement accuracy *1			±0.008 mm	±0.020 mm	±0.015 mm
	Part sizes			0402 (01005") to 15 x 15 mm	0.2 x 0.2 to 5.0 x 5.0 mm	0603 (0201") to 24 x 24 mm
	Throughput *1	NXT-H		5,200 cph	26,300 cph	11,500 cph
Panel sizes (L × W)		NXT-H		48 x 48 to 610 x 380 mm		
		NXT-Hw		48 x 48 to 610 x 610 mm		
Power				3-phase AC200 to 230 V ±10% (50/60 Hz)		
Air				0.5 MPa (ANR)		
Air consumption				20 L/min (ANR) *4		
Weight		NXT-H + MWU12i		1,930 kg *5	1,910 kg	1,910 kg

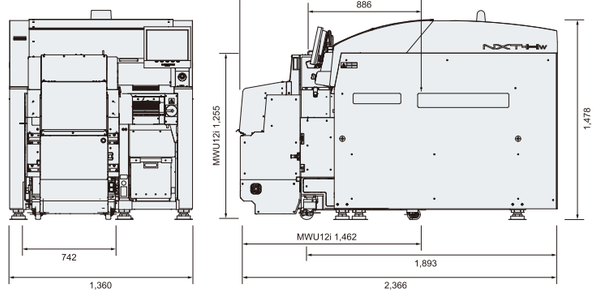
*1 Under optimum Fuji conditions.
*2 Please consult us if it is necessary to support 0.5 x 0.5 mm or less or thickness of 0.1 mm or less.
*3 Includes the flux dipping process.
*4 Add +90 L/min when using an MWU12i.
*5 When the configuration is NXT-H + MWU12i-FC.

Dimensions (mm)

NXT-H



NXT-Hw



FUJI CORPORATION
19 Chausuyama Yamamachi Chiryu, Aichi 472-8686 Japan
Tel: +81-566-81-2110
Fax: +81-566-83-1140

FUJI
innovative spirit

NXT-H

Fuji Ultra Accurate Placement Platform

Place SMDs and flip chips with one machine

NXT-H

This machine is based on the surface mount technology for placing SMD parts at high speed and incorporates semi-conductor technology for placing die parts with high accuracy. The NXT-H allows you to go from a batch process using dedicated machines to an innovative inline production process.

Supports panels up to 610 x 610 mm

Fan-out PLP
DCB

Wide range high-accuracy die placements (Face down)

type FC

Wide range high-speed die placements (Face up)

type SD

For complex modules such as communication and sensor modules

Multi chip SiP

Die placement (face down) + SMD placement

Flip chips
Flux transfer

type FC

For small power modules and sensor modules

Multi chip module
Power module

Die placement (face up) + SMD placement

type SD

Handles dies up to 24 x 24 mm

IGBT
Power module

Die placement (face up) + SMD placement

type LD

Flip Chip type FC

G04FQ head
4 nozzles

±0.008mm

Small Die type SD

H24S / H24G head
24 nozzles

13,400cph

Large Die type LD

H08MQ head
8 nozzles

8,700cph

Can load dies and SMDs with different supply methods

Supports wafers from 4 to 12 inches. These different sizes can be loaded in the same magazine by using adapters. Furthermore, up to 16 feeders for tape reels from 4 to 16 mm in width can be set on the fixed feeder table.

type FC type SD type LD

Modular concept that supports a many varieties of production types

- Inherits concepts from the NXT-series; our best-selling SMT mounter.
- Flexibly support different production types for flip chips, small dies, and large dies just by changing head types.

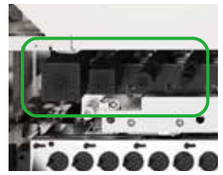
type FC type SD type LD

Supports flip chips and face-up supply

This machine can change between flip chip and face-up supply production methods as well as supply up to 25 different wafers.

type FC type SD type LD

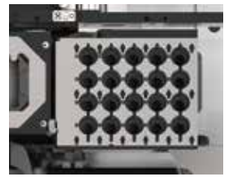
Automatic pusher pot exchange



This machine is equipped with a pusher pot changer and flip chip nozzle changer, so pusher pots and flip chip nozzles can be automatically exchanged during production.

type FC type SD type LD

Automatic nozzle exchange



There is a nozzle changer for automatically changing nozzles to match the parts being used.

type FC type SD type LD